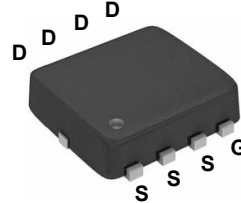
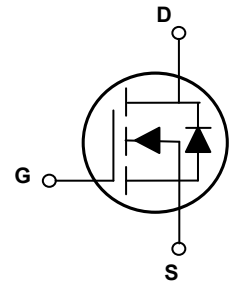


### Main Product Characteristics

$BV_{DSS}$	100V
$R_{DS(ON)}$	38m $\Omega$
$I_D$	16A



PPAK 3x3



Schematic Diagram

### Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



### Description

The GSFN0988 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supplies and a wide variety of other applications.

### Absolute Maximum Ratings ( $T_C=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Max.	Unit
Drain-Source Voltage	$V_{DS}$	100	V
Gate-Source Voltage	$V_{GS}$	+20/-12	V
Drain Current-Continuous ( $T_C=25^\circ\text{C}$ )	$I_D$	16	A
Drain Current-Continuous ( $T_C=100^\circ\text{C}$ )		10	
Drain Current-Pulsed <sup>1</sup>	$I_{DM}$	64	A
Single Pulse Avalanche Energy <sup>2</sup>	$E_{AS}$	34	mJ
Single Pulse Avalanche Current <sup>2</sup>	$I_{AS}$	26	A
Power Dissipation ( $T_C=25^\circ\text{C}$ )	$P_D$	32.5	W
Power Dissipation - Derate above 25 $^\circ\text{C}$		0.26	
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	62	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	3.85	$^\circ\text{C}/\text{W}$
Operating Junction Temperature Range	$T_J$	-55 To +150	$^\circ\text{C}$
Storage Temperature Range	$T_{STG}$	-55 To +150	$^\circ\text{C}$

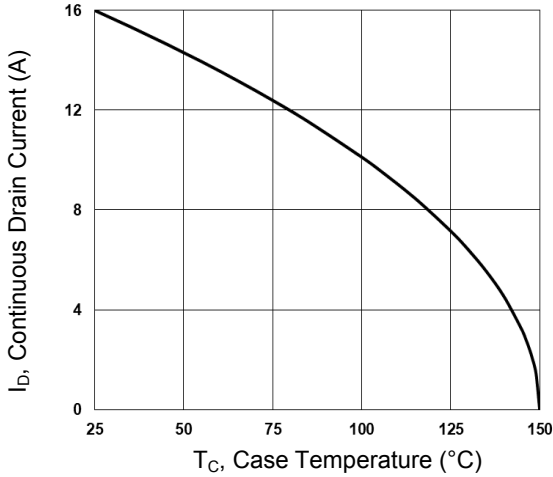
**Electrical Characteristics** ( $T_J=25^{\circ}\text{C}$  unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
<b>On / Off Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	100	-	-	V
Drain-Source Leakage Current	$I_{DSS}$	$V_{DS}=100V, V_{GS}=0V, T_J=25^{\circ}\text{C}$	-	-	1	$\mu A$
		$V_{DS}=80V, V_{GS}=0V, T_J=125^{\circ}\text{C}$	-	-	10	$\mu A$
Gate-Source Leakage Current	$I_{GSS}$	$V_{GS}=20V, V_{DS}=0V$	-	-	100	nA
Static Drain-Source On-Resistance <sup>3</sup>	$R_{DS(ON)}$	$V_{GS}=10V, I_D=10A$	-	32	38	m $\Omega$
		$V_{GS}=4.5V, I_D=8A$	-	49	63	
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=250\mu A$	1.0	1.6	2.5	V
Forward Transconductance	$g_{fs}$	$V_{DS}=10V, I_S=3A$	-	5	-	S
<b>Dynamic and Switching Characteristics</b>						
Total Gate Charge <sup>3,4</sup>	$Q_g$	$V_{DS}=50V, I_D=10A, V_{GS}=10V$	-	8	12	nC
Gate-Source Charge <sup>3,4</sup>	$Q_{gs}$		-	2.1	3.5	
Gate-Drain Charge <sup>3,4</sup>	$Q_{gd}$		-	2.3	4	
Turn-On Delay Time <sup>3,4</sup>	$t_{d(on)}$	$V_{DD}=50V, R_G=3.3\Omega, V_{GS}=10V, I_D=1A$	-	7.4	15	nS
Rise Time <sup>3,4</sup>	$t_r$		-	12	24	
Turn-Off Delay Time <sup>3,4</sup>	$t_{d(off)}$		-	23	46	
Fall Time <sup>3,4</sup>	$t_f$		-	16	32	
Input Capacitance	$C_{iss}$	$V_{DS}=20V, V_{GS}=0V, F=1\text{MHz}$	-	553	740	pF
Output Capacitance	$C_{oss}$		-	181	460	
Reverse Transfer Capacitance	$C_{rss}$		-	30	20	
Gate Resistance	$R_g$	$V_{GS}=0V, V_{DS}=0V, F=1\text{MHz}$	-	0.8	-	$\Omega$
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Continuous Source Current	$I_S$	$V_G=V_D=0V, \text{Force Current}$	-	-	16	A
Pulsed Source Current	$I_{SM}$		-	-	32	A
Diode Forward Voltage	$V_{SD}$	$V_{GS}=0V, I_S=1A, T_J=25^{\circ}\text{C}$	-	-	1	V
Reverse Recovery Time	$t_{rr}$	$V_{GS}=0V, I_S=10A, di/dt=100A/\mu s, T_J=25^{\circ}\text{C}$	-	30	-	nS
Reverse Recovery Charge	$Q_{rr}$		-	24	-	nC

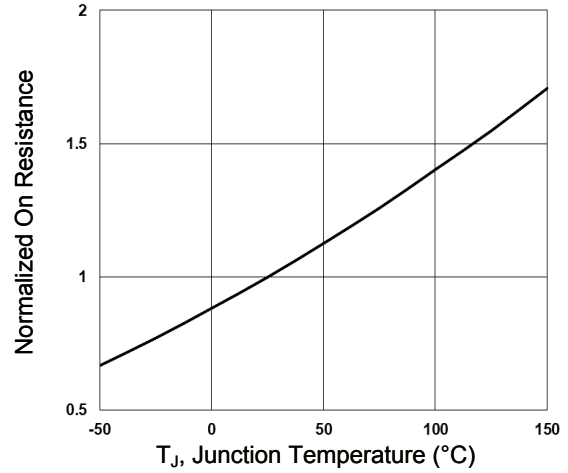
Note:

1. Repetitive rating: Pulsed width limited by maximum junction temperature.
2.  $V_{DD}=50V, V_{GS}=10V, L=0.1\text{mH}, I_{AS}=26A, R_G=25\Omega$ , starting  $T_J=25^{\circ}\text{C}$ .
3. Pulse test: pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
4. Essentially independent of operating temperature.

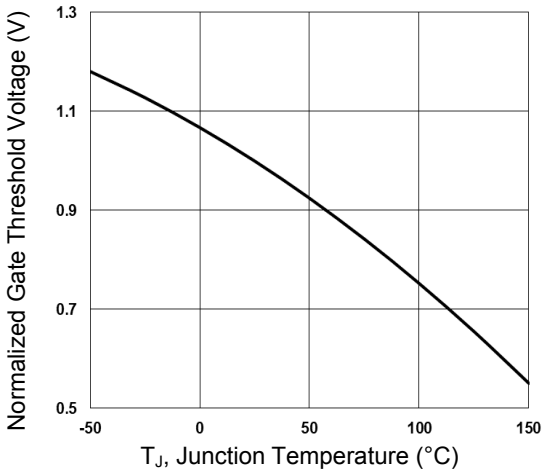
**Typical Electrical and Thermal Characteristic Curves**



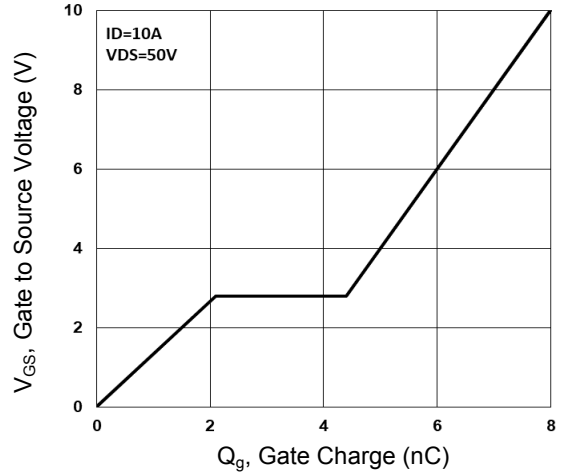
**Figure 1. Continuous Drain Current vs.  $T_C$**



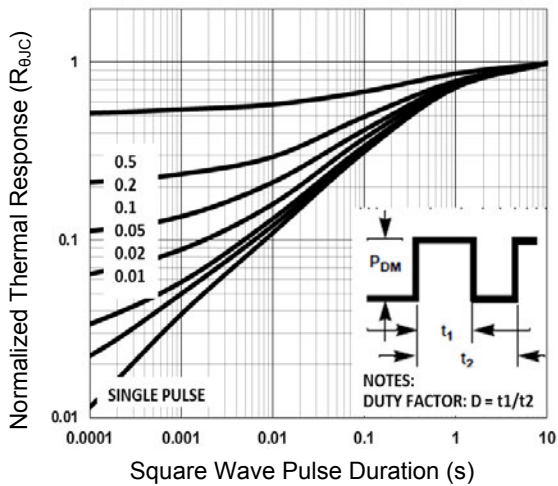
**Figure 2. Normalized  $R_{DSON}$  vs.  $T_J$**



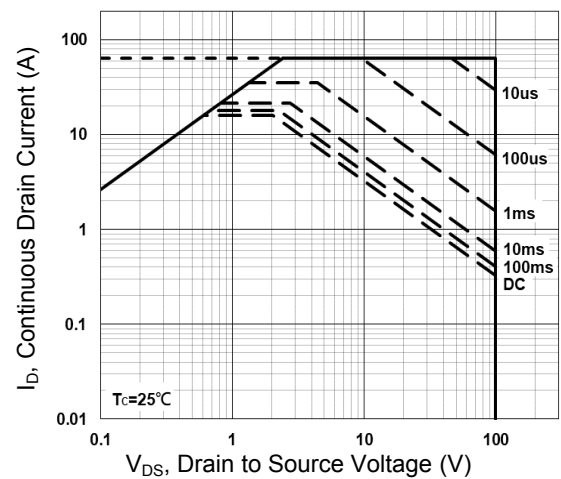
**Figure 3. Normalized  $V_{th}$  vs.  $T_J$**



**Figure 4. Gate Charge Characteristics**

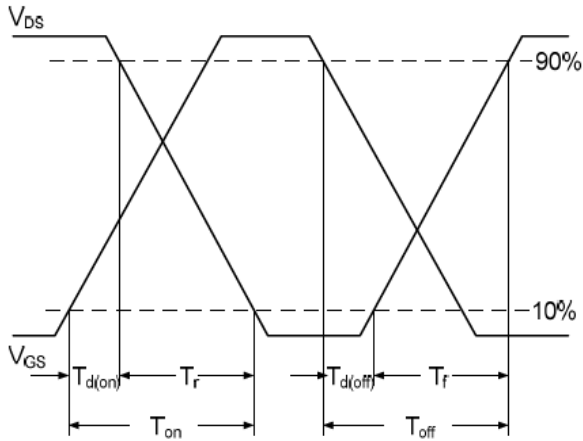


**Figure 5. Normalized Transient Response**

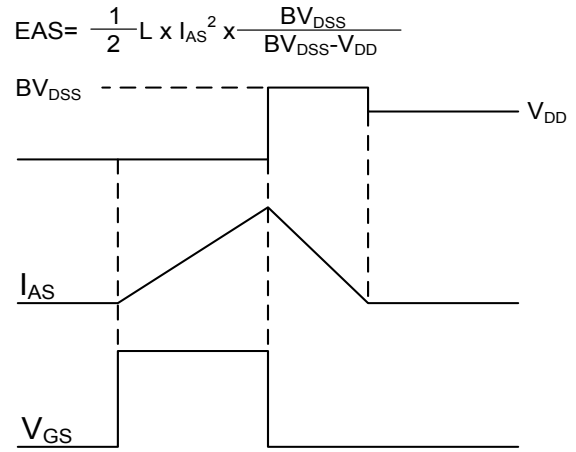


**Figure 6. Maximum Safe Operation Area**

**Typical Electrical and Thermal Characteristic Curves**

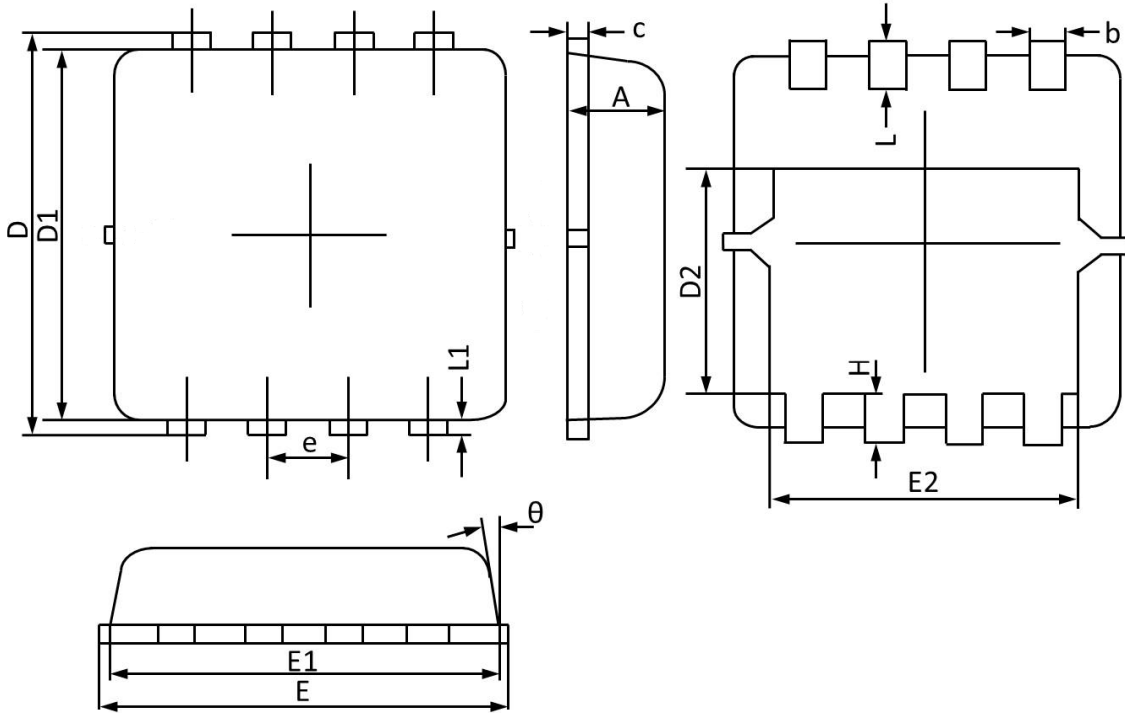


**Figure 7. Switching Time Waveform**



**Figure 8. EAS Waveform**

**Package Outline Dimensions PPAK3x3**



Symbol	Dimensions In Millimeters		Dimensions in Inches	
	MIN	MAX	MIN	MAX
A	0.700	0.900	0.028	0.035
b	0.240	0.350	0.009	0.014
c	0.100	0.250	0.004	0.010
D	3.050	3.450	0.120	0.136
D1	2.900	3.200	0.114	0.126
D2	1.350	1.850	0.053	0.073
E	3.000	3.400	0.118	0.134
E1	2.900	3.250	0.114	0.128
E2	2.350	2.600	0.093	0.102
e	0.650 BSC		0.026 BSC	
H	0.300	0.500	0.012	0.020
L	0.300	0.500	0.012	0.020
L1	0.070	0.200	0.003	0.008
θ	0°	12°	0°	12°

**Order Information**

Device	Package	Marking	Carrier	Reel QTY
GSFN0988	PPAK3x3	DC0988	Tape & Reel	3,000pcs